

Listing of Claims

The following listing of claims will replace all prior versions, and listings, of claims in the subject application:

1. (previously presented) A heat-sensitive stencil sheet having a porous resin layer provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the porous resin layer, wherein the amount of the adhesive ranges from 0.05 g/m^2 to 1.5 g/m^2 , and the bonding strength between the porous resin layer and the porous fiber layer ranges from 0.8 N/m to 50.0 N/m ,

wherein the porous resin layer includes a multiplicity of walls and ceilings which define cells, and

wherein said cell ceilings are bonded to the porous fiber layer by the adhesive.

2. (withdrawn) A heat-sensitive stencil sheet according to claim 1, wherein the adhesive is a primarily urethane adhesive of moisture-curable type.

3. (currently amended) A heat-sensitive stencil sheet according to claim 1 ~~or claim 2~~, wherein the adhesive is a primarily adhesive of ionizing radiation-curable type.

4. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous resin layer ranges from 0.5 g/m^2 to 10.0 g/m^2 by dry basis.

5. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous resin layer ranges from 1.0 g/m^2 to 5.0 g/m^2 by dry basis.

6. (original) A heat-sensitive stencil sheet according to claim 1, wherein the porous resin layer is a foamy film formed by applying a fluid containing an resin emulsion of water in oil type onto a thermoplastic film and drying it.

7. (original) A heat-sensitive stencil sheet according to claim 1, wherein amount of the porous fiber layer ranges from 1.0 g/m^2 to 15.0 g/m^2 .

8. (original) A heat-sensitive stencil sheet according to claim 1, wherein the amount of the porous fiber layer ranges from 3.0 g/m^2 to 10.0 g/m^2 .

9. (withdrawn) A method for fabricating a heat-sensitive stencil sheet according to claim 1 comprising the steps of; applying a coating liquid to one side of a thermoplastic film to form a porous resin layer attached to the thermoplastic film; and after at least the outermost surface of the porous resin layer is dried and cured, bonding the porous resin layer to a porous fiber layer coated with a adhesive.

10. (withdrawn) A thermal stencil printing apparatus loaded with a perforated heat-sensitive stencil master produced from a heat-sensitive stencil sheet, wherein the heat-sensitive stencil sheet is one as claimed in claim 1.

Claim 11-13 (canceled).

14. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein

pores of the porous resin layer have an average diameter in a range of 5 μm to 20 μm .

Claim 15 (canceled).

16. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous fiber layer have an average diameter in a range of 25 μm to 60 μm .

17. (currently amended) A heat-sensitive stencil sheet having a porous resin layer provided on one side of a thermoplastic resin film, and a porous fiber layer bonded by an adhesive to the surface of the porous resin layer,

wherein the porous resin layer includes a multiplicity of walls and ceilings which define cells, and

wherein said cell ceilings are bonded to the porous fiber layer by the adhesive.

Claim 18 (canceled).

19. (previously presented) A heat-sensitive stencil sheet according to claim 1, wherein pores of the porous fiber layer are connected in a depth direction and to a lesser degree in a transverse direction, so that sideward deviated penetration of ink in the stencil sheet is decreased.

20. (new) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer includes a polymer having radical polymeric double-bonds and containing mono-functional monomer or multi-functional monomer having relatively low molecular weight and are radically reactive with (meth)acrylates.

21. (new) A heat-sensitive stencil sheet according to claim 20, wherein said adhesive further includes a photo-polymerization initiator.

22. (new) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer includes a urethane acrylate oligomer.

23. (new) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer is an ionizing radiation-curable type adhesive cured by applying ionizing radiation ray from the porous fiber layer side.

24. (new) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer is an ionizing radiation-curable type adhesive cured by applying an electron beam.

25. (new) A heat-sensitive stencil sheet according to claim 17, wherein said adhesive bonding said porous fiber layer to said porous resin layer has a viscosity of 300 cps or higher.